

APPROVAL SHEET

MULTILAYER CERAMIC CAPACITOR

Automotive Grade, Soft Termination Type

(AEC-Q200 Qualified)



SAMWHA CAPACITOR .CO., LTD.

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* Notice

This sheet is for reference only and is subject to change or discontinuation without notice. Please contact our sales representatives for detailed information

< SPECIFICATION SUMMARY >									
SAMWHA Part no.	CQ3225X7R475K500ARK								
Туре		МІ	LCC for Automotive Application						
Items	Specification	Specification Unit Test Conditions							
Capacitance	4.7	μF	Testing Frequency : 1.0 ± 0.1KHz						
Capacitance Tolerance	± 10	%	Testing Voltage : 1.0 ± 0.2 Vrms Should be measured at 25°C.						
Dissipation Factor	Max. 12.5	%							
Insulation Resistance	More than 10.64	MΩ	Should be measured with a DC voltage not exceeding rated voltage at 25 $^{\circ}{\rm C}$ for 2 minutes of charging.						
	3.20 ± 0.50	L (mm)	Capacitance Tolerance Code page 4/15						
Chip Size	2.50 ± 0.30	W (mm)	Chip size page 5/15 Characteristics & Test Method page 6/15~9/15						
	2.00 ± 0.30	T (mm)							

% Thin Layer Large-Capacitance Type

PART NO. SAMWHA CQ3225X7R475K500ARK SPEC.

NO	REASON	CONTENTS	DATE OF APPROVAL	CHECKED	REMARKS
1	Initial written	full document	96. 03. 27		
2	Re-revision of approval document	full document	25. 02. 01		

General Description

1. General Code

*Caution : ECU/ Power Train/ Safety module/ Etc. Please contact sales representatives or product engineers before using these Automotive products

(1) Type Designation

<u>CQ</u>	<u>3225</u>	<u>X7R</u>	<u>475</u>	<u>K</u>	<u>500</u>	<u>A</u>	<u>R</u>	<u>K</u>
(1)	(2)	(3)	(4)	(5)	(6)	(7)	(8)	(9)

1) Multilayer Ceramic Capacitor (Automovie Grade)

2) Size Code : This is expressed in tens of a millimeter.

The first two digits are the length, The last two digits are width.

3) Temperautre Coefficient Code

Classification	Code	Temperature Range	Capacitance Tolerance
Class ∏	X7R	-55 to +125℃	± 15 %

4) Capacitance Tolerance Code

The nominal Capacitance Value in pF is expressed by three digit numbers.

The first two digits represents significant figures and the last digit denotes the number of zero

ex) 104 = 100000 pF /

R denotes decimal / 8R2 = 8.2 pF

5) Capacitance Tolerance Code

Code	Tolerance	Code	Code
В	± 0.1 pF	G	± 2.0 %
С	± 0.25 pF	J	±5%
D	±0.5 pF	К	± 10 %
F	± 1.0 %	М	± 20 %

6) Voltage Code

Code	6R3	100	160	250	350	500	101	201	251	501	631	102	202	302
Rate	DC	DC	DC	DC	DC	DC	DC	DC	DC	DC	DC	DC	DC	DC
Voltage	6.3V	10V	16V	25V	35V	50V	100V	200V	250V	500V	630V	1KV	2KV	3KV

7) Termination Code

N : Nickel-Tin Plate

A : Nickel-Tin Plate \rightarrow Soft Termination Type

8) Packing Code

R: 7" Reel Type, L: 13" Reel Type, B: Bulk Type

General Description

9) Thickness option

Thickne	ess (mm)	Codo	Thickne	ss (mm)	Code	
t	Tolerance (±)	Code	t	Tolerance (±)	Code	
0.50	0.10	Blank	1.35	0.20	Н	
0.60	0.10	A	1.60	0.30	I	
0.80	0.15	В	1.80	0.30	J	
0.85	0.15	В	2.00	0.30	К	
1.00	0.15	Е	2.50	0.30	L	
1.10	0.15	Е	2.80	0.30	М	
1.15	0.20	Е	3.20	0.40	Ν	
1.25	0.20	E	5.00	0.50	0	
1.30	0.20	E				

2. Temperature Characteristics

See Page 9 (Specifications and Test Methods : No.21)

3. Constructions and Dimensions

1) Dimensions



(Unit : mm)

	EIA Code	Dimension							
Size Code		Length			Width	1	T1(min)	G(min)	
		L	Tol(-)	Tol(+)	W	Tol(±)	1 (((((((((((((((((((((((((((((((((((((C(mm.)	
3225	1210	3.20	0.50	0.50	2.50	0.30	0.30	1.00	

(2) Construction of Termination



Spec	cifications	and Tes	t Methods (For Automo	otive Applications)							
	AFC-	0200	Specif	lication							
No.	Test	ltem	Class I	Class II		Test Methods			s and Conditions		
1	Pre-and P Electric	ost-Stress al Test			-						
		Appearance	No defects which may affect perform	nance	T	emperature			Max. o	perating tempe	rature ±3°C
		Capacitance Change	Within ±2.5% or ±0.25pF (Whichever is larger)	Within ±10.0% (*Within ±12.5%)	Measurement after test			Let sit for 24±2 hours at room			
2	High Temperature Exposure (Storage)	Q/D.F.	30pF min.: Q≧1000 30pF max.: Q≧400+20xC C: Nominal Capacitance (pF)	Rated Voltage 16V min.: 0.05 max. 10V: 0.075 max. *0.2 max.					-		
		I.R.	More than 10,000MΩ or 500Ω.F (*50 (Whichever is smaller)	0Ω.F)							
		Appearance	No defects which may affect perform	nance	Р	erform the 100)0 cycles acco	ordina ta	the fo	ur heat treatm	ents listed in
		Capacitance Change	Within ±2.5% or ±0.25pF (Whichever is larger)	Within ±10.0%	th	e following tab	1	2		3	4
	Temperature			Rated Voltage	┨┟	Temp.(℃)	-55+0/-3	25±	2	125+3/-0	25±2
3	Cycle	Q/D.F.	30pF min.:Q≧1000 30pF max.:Q≧400+20xC C: Nominal Capacitance (pF)	16V min.: 0.05 max. 10V: 0.075 max. *0.2 max.		Time(min)	15±3	1	Perfor	15±3 m the initial m	1 easurement
		I.R.	More than 10,000MΩ or 500Ω.F (*50 (Whichever is smaller)	м	Measurement after test			according to Note 1 for Class II Let sit for 24±2 hours at room temperature, then measure			
4	Destructiv Ana	e Physical ysis	No defects or abnormalities		Ρ	er EIA-469					
		Appearance	No defects which may affect perform	Т	Temperature Humidity			25~65°C 80~98%			
		Capacitance Change	Within ±3.0% or±0.30pF (Whichever is larger)	Within ±12.5%	C M	Cycle Time Measurement after test			24 hrs/cycle, 10 cycles Let sit for 24±2 hours at room temperature, then measure		
5	Moisture Resistance	Q/D.F.	30pF min.: Q≧350 10pF min. and 30pF max.: Q≧275+5/2×C 10pF max.: Q≧200+10×C C: Nominal Capacitance (pF)	Rated Voltage 16V min.: 0.05 max. 10V: 0.075 max. *0.2 max.		70 65 60 55 50 45 45 45 45 45 45 45 45 45 45 45 45 45	- 90-98%.F81	80-98%	% 80−98% ≫< 90−98% RH → RH >		
		I.R	More than 10,000MΩ or 500Ω.F (*50 (Whichever is smaller))Ω.F)			2 3 4 5 6 7 8	9 10 11 12 Time (! 13 14 15 (hrs)	16 17 18 19 20 21 2	2 23 24
		Appearance	No defects which may affect perform	nance	Т	emperature			85±3°0		
		Capacitance Change	Within ±3.0% or ±0.30pF (Whichever is larger)	Within ±12.5%	A A C	pplied Voltage pplied Time harge/Dischar	ge Current		80~85 Rated 1000+ 50mA	[∞] Voltage and 1 48/-0 hrs max.	.3+0.2/-0V
6	Humidity Bias	Q/D.F.	30pF min.: Q≧200 30pF max.: Q≧100+10/3×C C: Nominal Capacitance (pF)	Rated Voltage 16V min.: 0.05 max. 10V: 0.075 max. *0.2 max.	м	leasurement a	fter test		Let sit for 24±2 hours at room temperature, then measure		s at room easure
		I.R.	More than 1,000MΩ or 50Ω.F (*5Ω.F (Whichever is smaller)	:)							
		Appearance	No defects which may affect perform	nance	Т	emperature			Max. o	perating temp	o. ±3°C
		Capacitance Change	Within ±3.0% or ±0.30pF (Whichever is larger)	Within ±12.5%	A A	pplied Voltage pplied Time	e		Rated	Voltage x200' 48/-0 hrs	% (*150%)
7	High Temperature Operating Life	Q/D.F.	30pF min.:Q≧350 10pF min. and 30pF max.: Q≧275+5/2xC 10pF max.: Q≧200+10xC C: Nominal Capacitance (pF)	Rated Voltage 16V min.: 0.05 max. 10V: 0.075 max. *0.2 max.	C M In	harge/Dischar leasurement a itial Measuren	ge Current fter test nent for Class		50mA Let sit tempe Applie voltage Remov	max. for 24±2 hour rature, then m d 200% of the e for one hour ve and let sit f	s at room easure rated at 125±3°C or 24±2 hours
		I.R.	More than 1,000MΩ or 50Ω.F (*5Ω.F (Whichever is smaller)	;)					at roor	n temperature	, then measure

2. Sp	pecificatio	ns and T	est Methods (For Auto	motive Applications)							
	AEC-	0200	Specif	ication							
No.	Test	ltem	Class I	Class II	Test Methods	s and Conditions					
8	Externa	al Visua	No defects or abnormalities	•	Visual inspection						
9	Physical [Dimension	Within the specified dimensions		Using calipers						
		Appearance	No defects which may affect perform	nance							
		Capacitance Change	Within the specified tolerance								
10	Resistance to Solvent	Q/D.F.	30pF min.: Q≧1000 30pF max.: Q≧400+20xC C: Nominal Capacitance (pF)	Rated Voltage 50V: 0.025 max. 25V: 0.03 max. 16V: 0.035 max. 10V: 0.05 max. *0.125 max.	Per MIL-STD-202 Method 215	Method 215					
		I.R.	More than 10,000MΩ or 500Ω.F (*50	Ω.F) (Whichever is smaller)							
		Appearance	No defects which may affect perform	nance	Three shocks in each direction sho	ould be applied along 3					
		Capacitance Change	Within the specified tolerance		mutually perpendicular axes of the Wave form	test specimen (18 shocks) Half-sine					
11	Mechanical Shock	Q/D.F.	30pF min.: Q≧1000 30pF max.: Q≧400+20xC C: Nominal Capacitance (pF)	Rated Voltage 50V: 0.025 max. 25V: 0.03 max. 16V: 0.035 max. 10V: 0.05 max. *0.125 max.	Peak value Velocity change	1,500G 4.7m/s					
		I.R.	More than 10,000MΩ or 500Ω.F (*50	Ω.F) (Whichever is smaller)							
		Appearance	No defects which may affect perform	nance	Type of Vibration	10Hz to 2000Hz then 10Hz					
		Capacitance Change	Within the specified tolerance		Vibration time 2011/11. Total Amplitude 1.5mm Vibration directions and time This cycle should be performed						
12	Vibration	Q/D.F.	30pF min.: Q≧1000 30pF max.: Q≧400+20xC C: Nominal Capacitance (pF)	Rated Voltage 50V: 0.025 max. 25V: 0.03 max. 16V: 0.035 max. 10V: 0.05 max. *0.125 max.		times in each of three mutually perpendicular directions (total of 36 times)					
		I.R.	More than 10,000MΩ or 500Ω.F (*50	Ω.F) (Whichever is smaller)							
		Appearance	No defects which may affect perform	nance	Temperature	260±5°C					
		Capacitance Change	Within the specified tolerance	Within the specified tolerance	Measurement after test	10±1sec. Let sit for 24±2 hours at room temperature, then measure					
13	Resistance to Solder Heat	Q/D.F.	30pF min.: Q≧1000 30pF max.: Q≧400+20xC C: Nominal Capacitance (pF)	Rated Voltage 50V: 0.025 max. 25V: 0.03 max. 16V: 0.035 max. 10V: 0.05 max. *0.125 max.	Initial measurement	Perform the initial measurement according to Note 1 for Class II					
		I.R.	More than 10,000MΩ or 500Ω.F (*50	Ω.F) (Whichever is smaller)							
		Appearance	No defects which may affect perform	nance	Perform the 300 cycles according	to the two heat treatments listed in the					
		Capacitance Change	Within ±2.5% or ±0.25pF (Whichever is larger)	Within ±15%	Tollowing table. Step Temp.(°C) -5	1 2 5+0/-3 125+3/-0					
14	Thermal Shock	Q/D.F.	30pF min.: Q≧1000 30pF max.: Q≧400+20xC C: Nominal Capacitance (pF)	Rated Voltage 50V: 0.025 max. 25V: 0.03 max. 16V: 0.035 max. 10V: 0.05 max. *0.125 max.	Time(min.) Transfer Time Measurement after test Initial measurement	15±3 15±3 20sec. max. Let sit for 24±2 hours at room temperature, then measure. Perform the initial measurement according to Note 1 for Class II					
		I.R.	More than 10,000MΩ or 500Ω.F (*50	Ω.F) (Whichever is smaller)	_						

2. Sp	2. Specifications and Test Methods (For Automotive Applications)											
	AEC-0200		Specif	ication								
No.	Test	ltem	Class I	Class II	Test Methods and Conditions							
		Appearance	No defects which may affect perform	hance								
		Capacitance Change	Within the specified tolerance									
15	15 ESD Q/D.1		30pF min.: Q≧1000 30pF max.: Q≧400+20xC C: Nominal Capacitance (pF)	Pe	er AEC-Q200-(002						
		I.R.	More than 10,000MΩ or 500Ω.F (*50	Ω .F) (Whichever is smaller)								
16	Solder	rability	95% of the terminations is to be sold	ered evenly and continuously.	 (a) Preheat at 155°C for 4 hours, and then immerse the capacitor in a solution of ethanol and rosin. Immerse in eutectic solder solution for 5+0/-0.5 seconds at 235±5°C. (b) Steam aging for 8 hours, and then immerse the capacitor in a solution of ethanol and rosin. Immerse in eutectic solder solution for 5+0/-0.5 seconds at 235±5°C. (c) Steam aging for 8 hours, and then immerse the capacitor in a solution of ethanol and rosin. Immerse in eutectic solder solution for 12±5 seconds at 260±5°C. 				e capacitor in a er pacitor in a er solution for pacitor in a er solution for 120			
		Appearance	No defects which may affect perform	nance	Th	ne capacitance	/Q/D.F. should be m	easured at 25°C a	at the frequency			
		Capacitance Change	Within the specified tolerance	e specified tolerance		nd voltage sho Class	wn in the table. Capacitance (C)	Frequency	Voltage			
					1ŀ		C<1000pF	1±0.1MHz	0.5~5Vrms			
		Q/D.F.				Class I	C≥1000pF	1±0.1kHz	1±0.2Vrms			
			30pF min.: Q≧1000 30pF max.: Q≧400+20xC C: Nominal Capacitance (pF)	Rated Voltage 50V: 0.025 max. 25V: 0.03 max. 16V: 0.035 max. 10V: 0.05 max. *0.125 max	IГ	Class II	C≤10µF	1±0.1kHz	0.5~1.0Vrms			
17	Electrical Characterizati on				C>10µF 1 Measurement after test Take (Class Initial measurement Perfor accor			120±24Hz Take it out and se (Class II) then me Perform the initial according to Note	0.5±0.1Vrms t it for 24±2 hours asure measurement 1 for Class II			
		I.R. at 25℃	More than 100,000MΩ or 1,000Ω.F (Whichever is smaller)	More than 10,000MΩ or 500Ω.F (*50Ω.F) (Whichever is smaller)	Applied VoltageRated voltageCharging Time2min.Charge/Discharge Current50mA max.							
		I.R. at 125℃	More than 10,000MΩ or 1,000Ω.F (Whichever is smaller)	More than 1,000MΩ or 10Ω.F (*1Ω.F) (Whichever is smaller)								
		Voltage proof	No dielectric breakdown or mechanic	cal breakdown	Applied Voltage250% of the rated voltageApplied Time1 to 5sec.Charge/Discharge Current50mA max.							
		Appearance	No defects which may affect perform	Ap 60	oply a force in t	the direction shown i	n the following figu	ire for				
18	Board Flex					Support	Solder Chip F	stinted circuit board before ter	ting			
		Capacitance Change	Within ±5.0% or ±0.5pF (Whichever is larger)	Within the specified tolerance		1.6 Printed circuit board	Radus 340	nobe to exert bending force				
		Appearance	No defects which may affect perform	ance	Aŗ	plied Force		18N [*]				
19	Terminal	Capacitanco	Within +5.0% or +0.5pF		Ho	olding Time *10N for 1608	size (EIA:0603)	60±1 seconds.				
13	Strength	Change	(Whichever is larger)	Within the specified tolerance	1	2N for 1005	size (EIA:0402)					

2. Specifications and Test Methods (For Automotive Applications)														
	No. AEC-Q200 Test Item		AFC-0200											
No.				Class I		Class II			Test Methods and Conditions					
			The ch	nip endure following for	rce.				Apply a force	as shown	in the follow	ina fiaure		
			Chip Length Thi		ckness (T)	Force		(i) Chip Leng	th : 2.5mm	max.	(ii) Chip Le	ength : 3.2m	nm min. mm/c	
				2.5mm max	Т	[′] ≤0.5mm	8N		Beam Sp		11/5	Dealli	Speed . 2.5	1111/5
20	Beam Lo	oad Test		2.51111 1102.	٦	Г>0.5mm	20N			Å				
				3.2mm min.	Т	<1.25mm	15N		<u> </u>	<u> </u>	Iron Board			
						T≥1.25	54.5N					0.6		
									(i) Class I				∣◄━►∣	
		Capacitance Change	e		Within ±15%			 (i) Class I The temperature coefficient is determined using the capacitance measured in step 3 as a reference. When cycling the temperature sequentially from step 1 through 5, the capacitance should be within the specified tolerance for the temperature coefficient. The capacitance drift is calculated by dividing the differences between the maximum and minimum measured values in steps 1, 3 and 5 by the 						
		Temperature Coefficient	0±30 p	opm/℃					capacitance	value in ste	p 3.			
	Capacitance Temperature	ance ature eris-							Step	1	2	3	4	5
21	Characteris-								Temp.(℃)	25±2	-55±3	25±2	125±3	25±2
		Capacitance Drift	Within ±0.2% or ±0.05pF (Whichever is larger)				 (ii) Class II The ranges of capacitance change compared with the 25°C value over the temperature range from -55°C to 125°C. Initial measurement Perform the initial measurement according to Note 1 for Class 			C value asurement rr Class II.				

In the case of "*" is specifications for "Thin Layer Large Capacitance Type"

Note 1. Initial Measurement for Class II Perform a heat treatment at 150+0/-10oC for one hour, and then let sit for 24±2 hours at room temperature, then measure.

"Following the International standards, the title of each test item is subject to change"

3. Packing

(1) Bulk Packing

1 1000 pcs per polybag

2 5 polybags per inner box

3 10 inner boxes per out box

(2) Reel Packing

1 8~10 reels per inner box

② 6 inner boxes per out box

(3) Reel Dimensions

(Unit : mm) EIA Code Mark Size Code А В С D Е W 7 " Reel 1005~3225 0402~1210 Φ178±2 Φ50Min Φ13±0.5 Φ21±0.8 2±0.5 10±1.5 13 " Reel 1005~3225 0402~1210 Φ330±2 Φ70Min Φ13±0.5 Φ21±0.8 2±0.5 10±1.5

(4) Number of Package

Sizo Codo	EIA Codo	7"	13"		
312e C00e	EIA Code	Quantity(pcs)/Reel	Quantity(pcs)/Reel		
1005	0402	10,000	50,000		
1608	0603	4,000	15,000		
2012	0805	3,000 ~ 4,000	8,000 ~ 15,000		
3216	1206	2,000 ~ 4,000	6,000 ~ 10,000		
3225	1210	1,000 ~ 3,000	4,000 ~ 10,000		

Packing

(5) Tape Dimensions



Size Code	EIA Code	사이즈	두께	А	В	С	D	E	F	G	Н	J
CS0603	CC0201	0603	all	0.7±0.02	0.4±0.02	8±0.1	3.5±0.05	1.75±0.05	2±0.05	2±0.05	4±0.1	1.55±0.03
CS1005	CC0402	1005	all	1.12±0.03	0.62±0.03	8±0.1	3.5±0.05	1.75±0.05	2±0.05	2±0.05	4±0.1	1.55±0.03
CS1005	CC0402	1005	all	1.12±0.03	0.58±0.03	8±0.1	3.5±0.05	1.75±0.05	2±0.05	2±0.05	4±0.1	1.55±0.03
CS1005	CC0402	1005	all	1.16±0.03	0.66±0.03	8±0.05	3.5±0.05	1.75±0.05	2±0.05	2±0.05	4±0.1	1.55±0.03
CS1608	CC0603	1608	A, B	1.8±0.05	0.95±0.05	8±0.1	3.5±0.05	1.75±0.05	2±0.05	2±0.05	4±0.1	1.55±0.03
CS1608	CC0603	1608	A, B	1.78±0.05	0.92±0.05	8±0.1	3.5±0.05	1.75±0.05	2±0.05	2±0.05	4±0.1	1.55±0.03
CS1608	CC0603	1608	В	1.9±0.05	1.1±0.05	8±0.2	3.5±0.05	1.75±0.1	4±0.1	2±0.05	4±0.1	1.5+0.1
CS1608	CC0603	1608	В	1.9±0.05	1.1±0.05	8±0.1	3.5±0.05	1.75±0.05	4±0.1	2±0.05	4±0.1	1.55±0.03
CS2012	CC0805	2012	E	2.25±0.1	1.35±0.1	8±0.1	3.5±0.05	1.75±0.1	4±0.1	2±0.05	4±0.05	1.5±0.1
CS2012	CC0805	2012	Ш	2.4±0.1	1.6±0.1	8±0.1	3.5±0.05	1.75±0.1	4±0.1	2±0.05	4±0.05	1.5±0.1
CS2012	CC0805	2012	ш	2.25±0.1	1.35±0.1	8±0.1	3.5±0.05	1.75±0.1	4±0.1	2±0.05	4±0.1	1.5+0.1
CS2012	CC0805	2012	Ш	2.25±0.05	1.53±0.08	8±0.1	3.5±0.05	1.75±0.1	4±0.1	2±0.05	4±0.1	1.5+0.1
CS2012	CC0805	2012	А	2.3±0.05	1.55±0.05	8±0.1	3.5±0.05	1.75±0.05	4±0.1	2±0.05	4±0.1	1.55±0.03
CS2012	CC0805	2012	В	2.3±0.05	1.55±0.05	8±0.1	3.5±0.05	1.75±0.05	4±0.1	2±0.05	4±0.1	1.55±0.03
CS3216	CC1206	3216	ш	3.5±0.1	1.88±0.1	8±0.1	3.5±0.05	1.75±0.1	4±0.1	2±0.05	4±0.05	1.5±0.1
CS3216	CC1206	3216	-	3.45±0.1	1.75±0.1	8±0.1	3.5±0.05	1.75±0.1	4±0.1	2±0.05	4±0.05	1.5±0.1
CS3216	CC1206	3216	I	3.7±0.1	1.85±0.1	8±0.1	3.5±0.05	1.75±0.1	4±0.1	2±0.05	4±0.05	1.5±0.1
CS3225	CC1210	3225	L	3.58±0.1	2.75±0.1	8±0.1	3.5±0.05	1.75±0.1	4±0.1	2±0.05	4±0.05	1.5±0.1
CS3225	CC1210	3225	J	3.58±0.1	2.85±0.1	8±0.1	3.5±0.05	1.75±0.1	4±0.1	2±0.05	4±0.05	1.5±0.1
CS3225	CC1210	3225	L	3.5±0.1	2.7±0.1	8±0.1	3.5±0.05	1.75±0.1	4±0.1	2±0.05	4±0.05	1.5±0.1
CS4532	CC1812	4532	М	4.9±0.1	3.6±0.1	12±0.1	5.5±0.05	1.75±0.1	8±0.1	2±0.05	4±0.05	1.5±0.1



(6) Cover tape peel-off Strength

1. Peeling strength

10 g.f to 70 g.f

2. Measurement Method



Packing

(7) Packing Label(* Reference image)



(8) Packing Box



1) Customer

② Part No.③ Lot No

④ Q/ty

Inner box drawing



Out box drawing

Packing Box Dimensions

(Unit : mm)

		Size					
	Division	L	W	Н			
Inner Box	7 " Reel Box (in 5 reels)	183	65	185			
	7 " Reel Box (in 10 reels)	185	135	185			
	13 " Reel Box	330	65	337			
Out Box	7 " Reel Box	430	390	210			
	13 " Reel Box	350	350	360			

Caution

Storage Condition

When solderability is considered, capacitor are recommended to be used in 12 months.

MLCC should be stored at 5~40 °C with a relative humidity of 20~70%.

High humidity can reduce solderability due to oxidation.

Use the product within 6 months of the outgoing delivery date, and check the packaging if more than 6 months have passed.

It's recommended to use within 1 year to avoid solderability issues from long-term storage.

If over 1 year, verify solderability before use.

▶ The Regulation of Environmental Pollution Materials

Never use materials mentioned below in MLCC products regulated this document.

Pb, Cd, Hg, Cr+6, PBB(Polybrominated biphenyl), PBDE(Polybrominated diphenyl ethers), asbestos

Reflow Soldering

1. The sudden temperature change easily causes mechanical damages to ceramic components. Therefore, the preheating procedures should be required for the soldering of ceramic components.

2. Please refer to the recommended soldering profiles as shown in figures, and keep the temperature difference(\triangle T) within the range recommended in Table 1.

Table I

Size code (EIA Code)	Temperature Difference
0603, 1005, 1608, 2012, 3216	∆T≤150°C
3225 size and over	∆T≤130°C

Recommended Conditions

Size code (EIA Code)	Lead Free Solder				
Peak Temperature	240 - 260°C				
Atmosphere	Air or N ₂				
* Compliant Standard (ESD3)					



Peak Temperature	240 - 260°C				
Atmosphere	Air or N ₂				
* Compliant Standard JESD22					

Compliant Standard JESD22

Flow Soldering

1. The sudden temperature change easily causes mechanical damages to ceramic components. Therefore, the preheating procedures should be required for the soldering of ceramic components.

2. Please refer to the recommended soldering profiles as shown in figures, and keep the temperature difference($\triangle T$) within the range recommended in Table 2.

Table 2

Size code	Temperature Difference
1608, 2012, 3216	∆T≤150°C

Recommended Conditions

Conditions	Lead Free Solder		
Soldering Peak Temperature	250 - 260°C		
Atmosphere	Air or N ₂		

*Lead Free Solder : Sn-3.0Ag-0.5Cu



Notice

Land Dimension



Table . Reflow Soldering Method

Chip size [mm]	Chip tol. [mm]	a [mm]	b [mm]	с [mm]
0000	±0.03	0.2~0.25	0.2~0.3	0.25~0.35
0603	±0.05/±0.09	0.23~0.3	0.25~0.35	0.3~0.4
1005	±0.1	0.3~0.5	0.35~0.45	0.4~0.6
1005	±0.2	0.4~0.6	0.4~0.5	0.5~0.7
1609	±0.1	0.6~0.8	0.6~0.7	0.6~0.8
1608	±0.2	0.7~0.9	0.7~0.8	0.8~1.0
2012	±0.1	0.9~1.3	0.6~0.8	1.2~1.4
2012	±0.2	1.0~1.4	0.6~0.8	1.2~1.4
2216	±0.2	1.8~2.0	0.9~1.2	1.5~1.7
3210	±0.3	1.9~2.1	1.0~1.3	1.7~1.9
3225		2.0~2.4	1.0~1.2	1.8~2.3
4532		3.0~3.5	1.2~1.4	2.3~3.0
5750		4.0~4.6	1.4~1.6	3.5~4.8

*Please confirm the suitable land dimensions, which are determined through the evaluation of the actual SET and PCB

Note

(1) 'Aging'/'De-aging' behavior of high dielectric constant type MLCCs

(Typically represented by X7R temperature characteristic of which main composition is BaTiO₃)

'Aging' / 'De-aging' Behavior of high dielectric MLCCs Please note that high dielectric type dielectric ceramic capacitors have a "normal" 'aging' behavior / characteristic, that is; their capacitance value decreases with time from its value when it was first manufactured. From that date, the capacitance value begins to decrease at a logarithmic rate defined by:

 $Ct = C_{24} (1 - k \log 10 t)$

where,

- Ct : Capacitance value, t hours after the start of 'aging
- C₂₄ : Capacitance value, 24 hours after its manufacture
- k : Aging constant (capacitance decrease per decade-hour)
- t : time, in hours, from the start of 'aging'



The capacitance value can be restored (also known as 'de-aged') by exposing the component to elevated temperatures approaching its curie temperature (approximately 120°C). This 'de-aging' can occur during the component's solder-assembly onto the PCB, during life or temperature cycle testing, or by baking at 150°C for about 1 hour.

(2) Caution of Application

Please contact our sales representatives or product engineers before using the products in this catalog for the applications listed below, which require especially high reliability for the prevention of defects which might directly damage a third party's life, body or property, or when one of our products is intended for use in applications other than those specified in this catalog.

- (a) Aircraft equipment (b) Aerospace equipment (c) Undersea equipment (d) Power plant equipment
- (e) Medical equipment (F) Transportation equipment (vehicles, trains, ships, etc.)
- (9) Traffic signal equipment (b) Disaster prevention / crime prevention equipment
- Industrial equipment (Conveyors, Robot equipment, etc)
 Led equipment
- (k) Application of similar complexity and/or reliability requirements to the applications listed above